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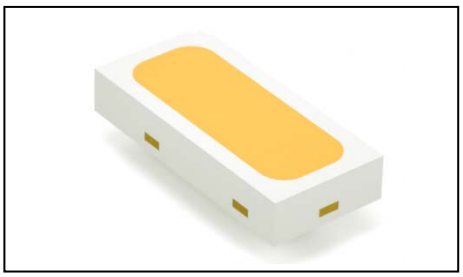
1. Description

1.1



The Yellow LED, which was fabricated by using a blue chip and the phosphor.

Product Package: 3.00mmX1.40mmX0.52mm.

LED 3.00mmX1.40mmX0.52mm.

1.2Features

► EMC Package. EMC

►Extremely wide viewing angle.

►Suitable for all SMT assembly and solder process. SMT

►Available on tape and reel.

►Moisture sensitivity level: Level 2. Level2

►RoHS compliant. RoHS

►Qualifications: The product qualification test plan is based on the guidelines of AEC-Q102 Stress Test Qualification for Automotive Grade Discrete Semiconductors

AEC-Q102

1.3Application

► Automotive Lighting Interior and Exterior.

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1.4Package Dimension

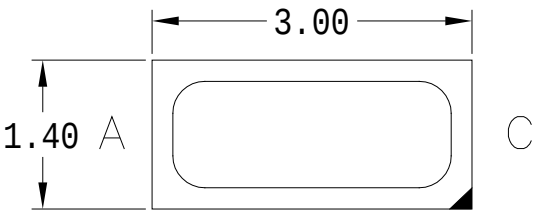

Fig.1—1 Top View

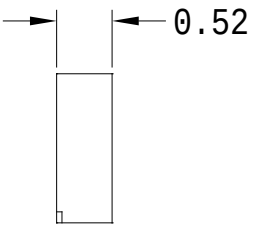

Fig.1—2 SideView

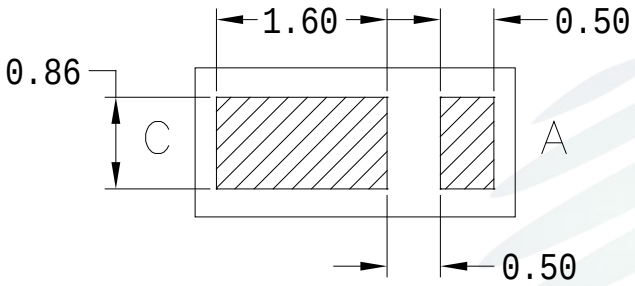

Fig.1—3 Bottom View

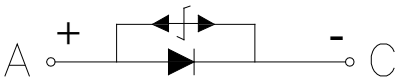

Fig.1—4 Polarity

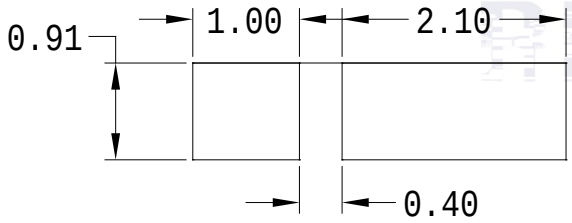

Fig.1—5 Soldering Patterns

Notes

1. All dimensions units are millimeters.

2. All dimensions tolerances are ±0.2mm unless otherwise noted. ±0.2

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1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.

2. The above forward voltage measurement allowance tolerance is ±0.1V. ± 0.1V.

3. The above color coordinates measurement allowance tolerance is ±0.005. ± 0.005.

4. The above luminous flux measurement allowance tolerance ±10%. ± 10%.

5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.

6. All measurements were made under the standardized environment of Refond.

7.When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED

8.At 25℃, pulse mode test, photoelectric conversion efficiency ηe=27%. 25
30%

9.Thermal resistance values (Rth JS Electrical) measure current is 140mA ,Temperature constant at 25°C. (Rth JS Electrical) 140mA 25°C

1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=140mA)

BIN (IF=140mA)

Table 1-3

V_F V	G0	H0	I0
	2.8-3.0	3.0-3.2	3.2-3.4
φ lm	NB	OA	OB
	40.9-45.3	45.3-50	50-55.3

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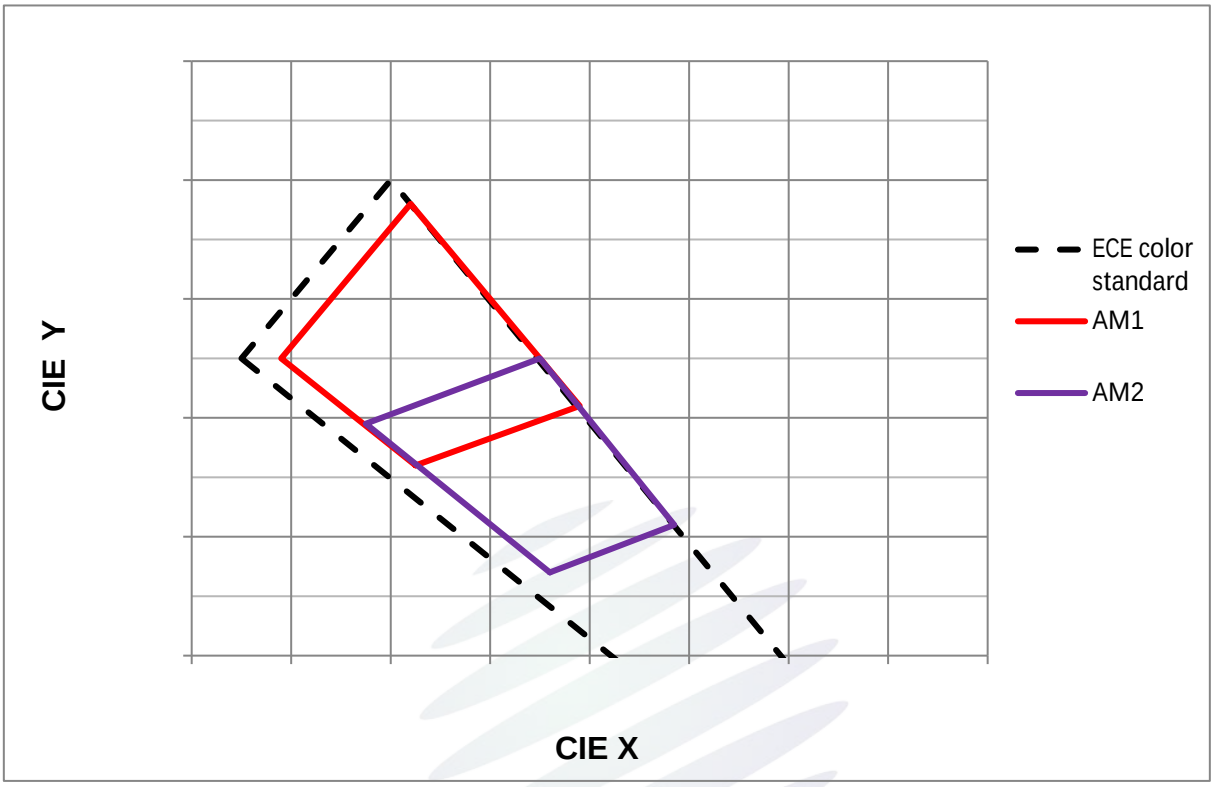

Fig. 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-4

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
AM1	0.5625	0.4160	0.5490	0.4250	0.5620	0.4380	0.5790	0.4210
AM2	0.5760	0.4070	0.5575	0.4195	0.5750	0.4250	0.5885	0.4110

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1.7 Typical Optical Characteristics Curves

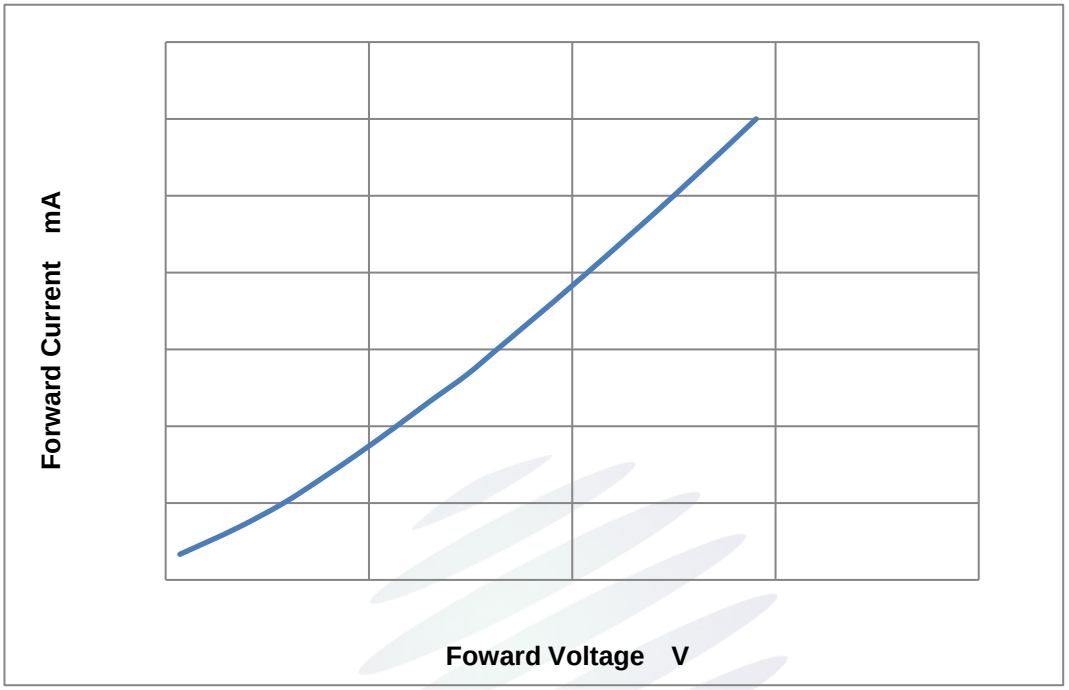

Fig. 1-7 Forward Voltage Vs Forward Current

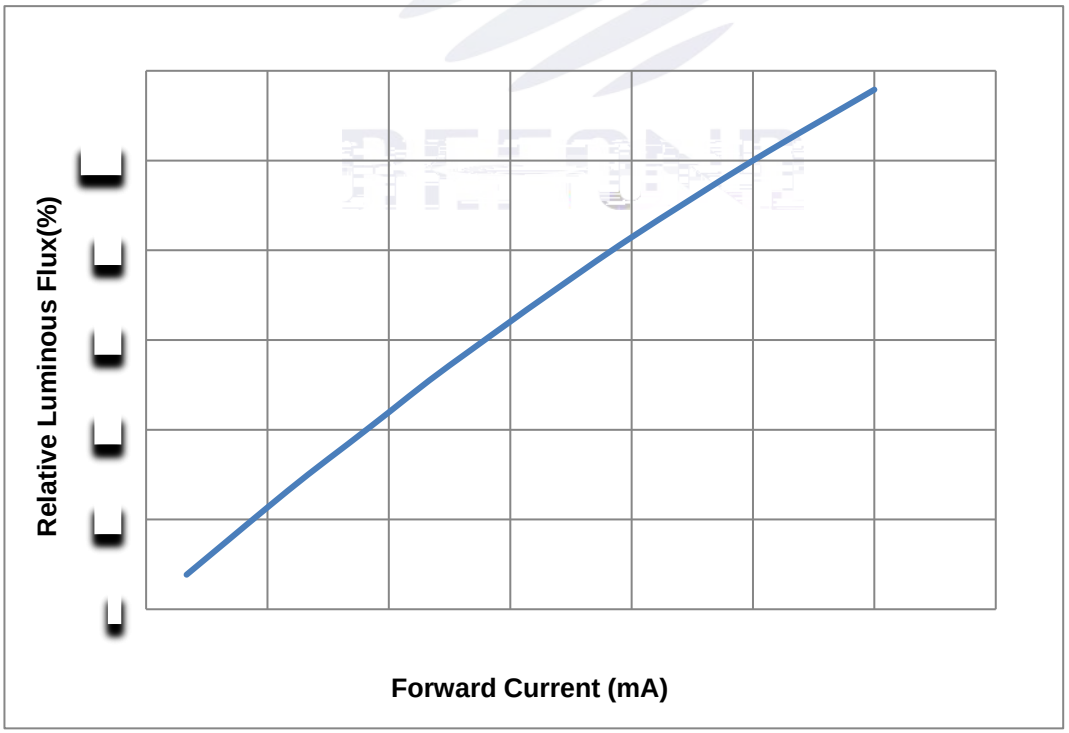

Fig. 1-8 Forward Current Vs Relative Intensity

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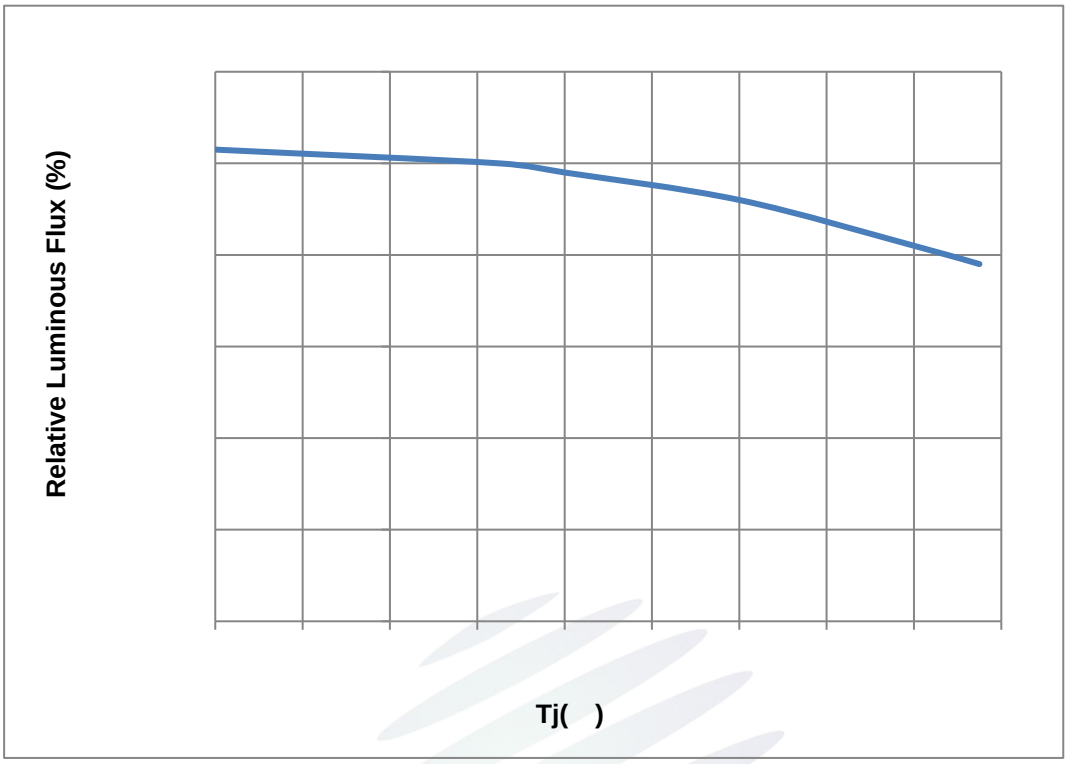

Fig. 1-9 Solder Temperature Vs Relative Intensity

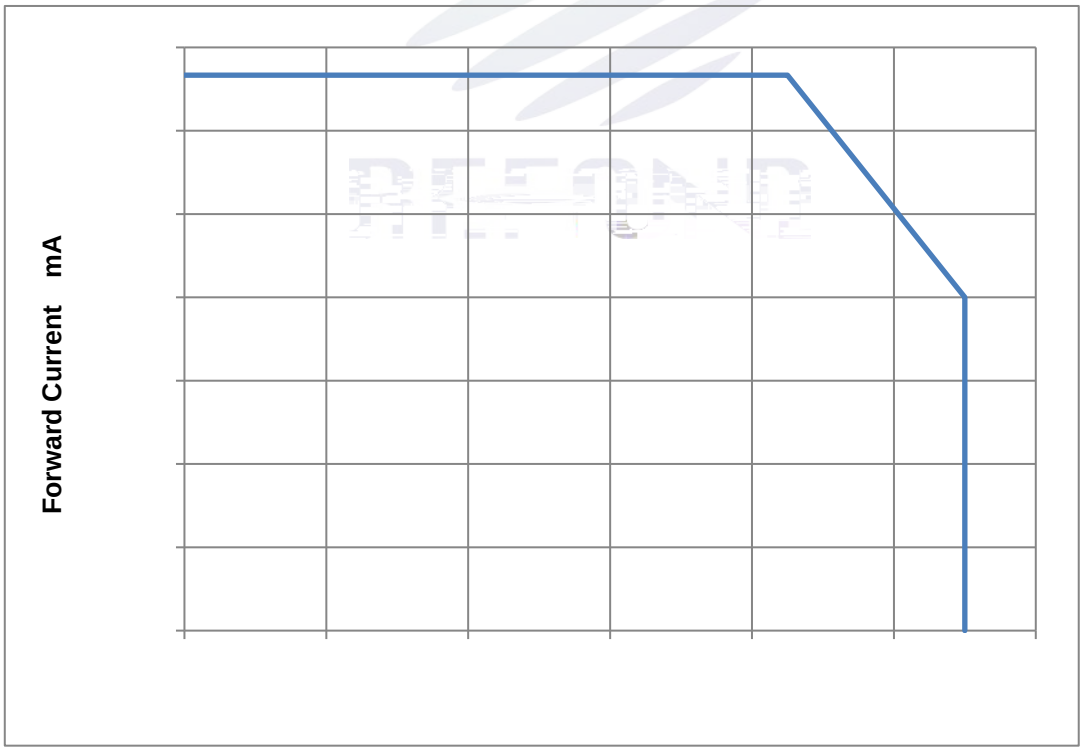

Fig. 1-10 Solder Temperature Vs Forward Current

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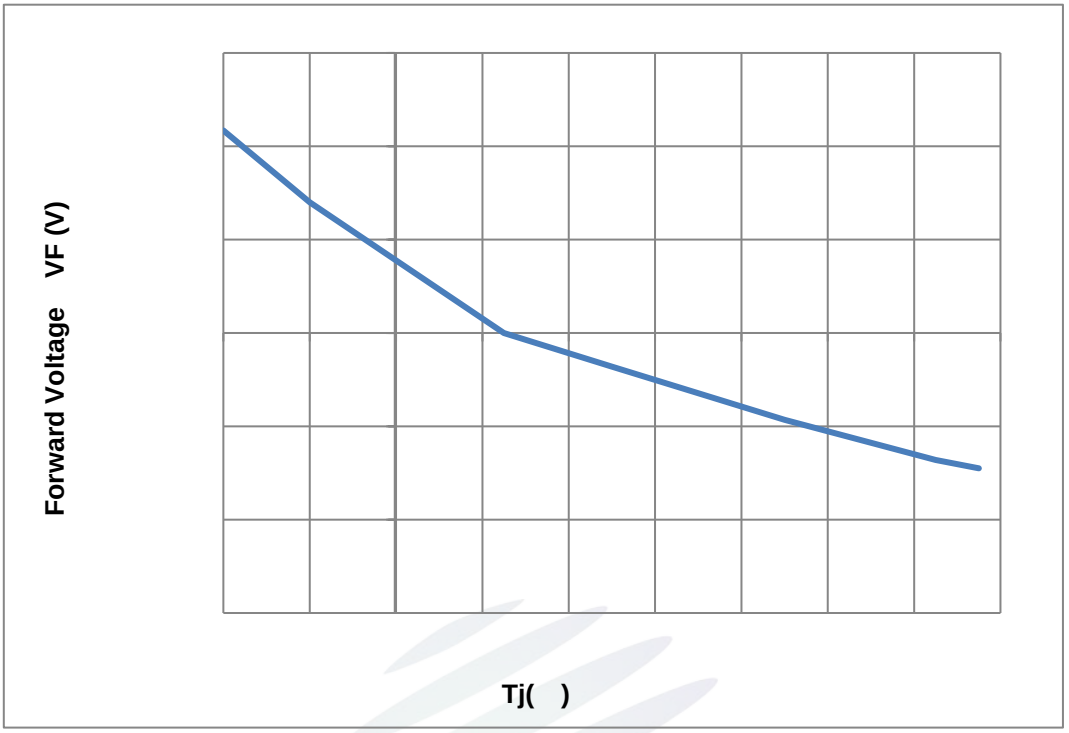

Fig. 1-11 Voltage shift Vs Junction Temperature

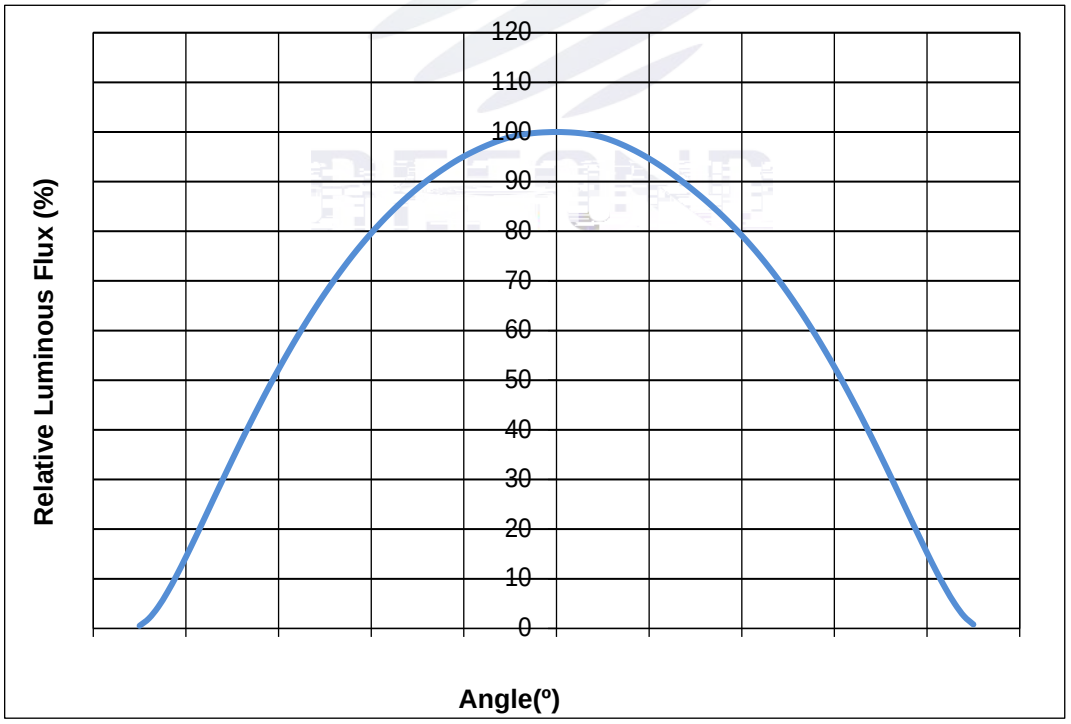

Fig. 1-12 Radiation diagram

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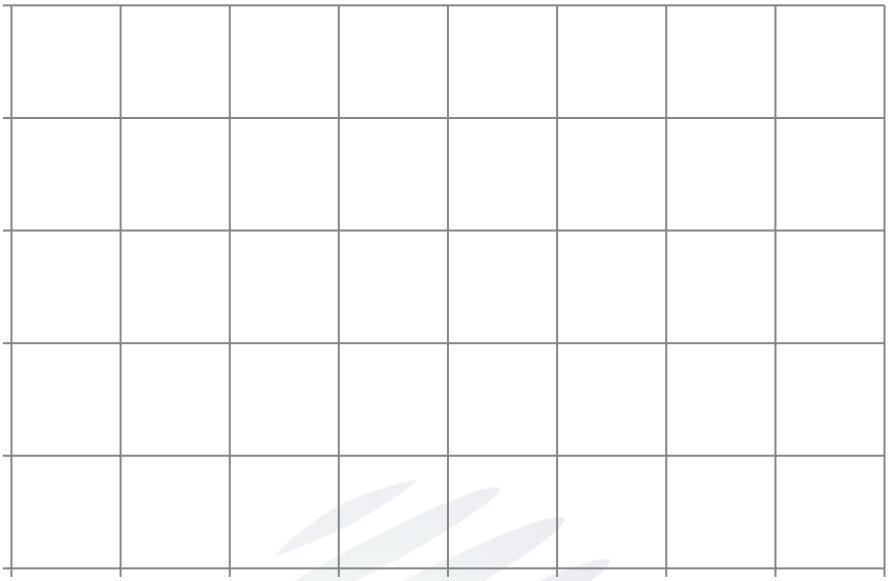

Fig. 1-15 Spectrum Distribution

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2. Packaging

2.1 Packaging Specification

Package:5000pcs/reel. 5000pcs

2.1.1Carrier Tape Dimension

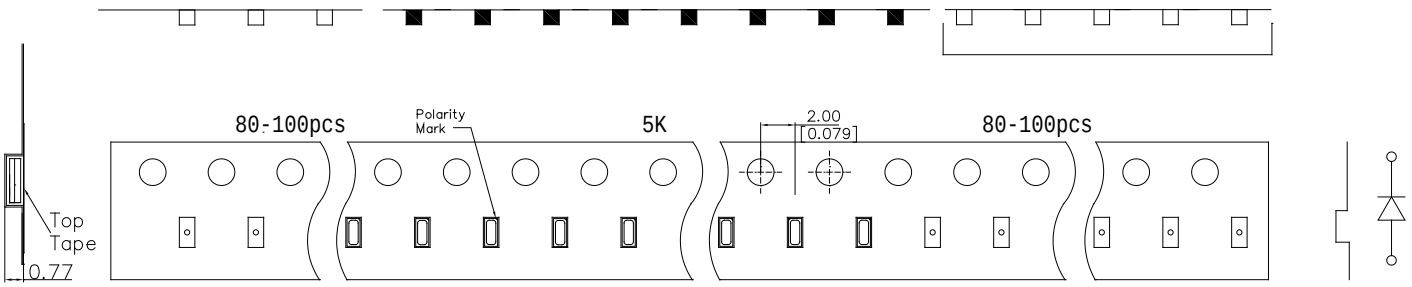

Fig.2-1 Carrier Tape Dimension

2.1.2Reel Dimension

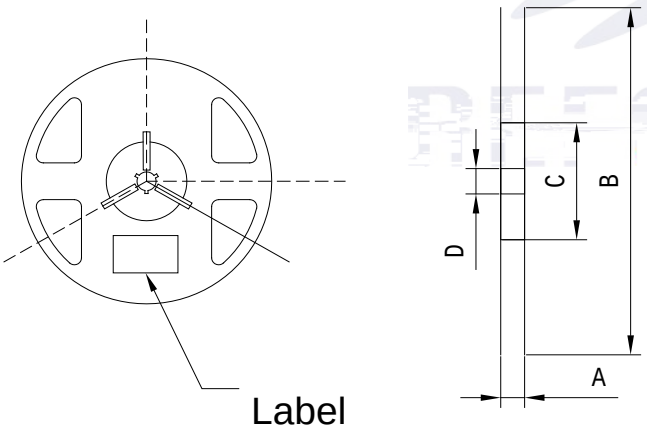

Fig.2-2Reel Dimension

Table 2-1Reel Dimension

A	8.0 ± 0.1mm
B	178 ± 1mm
C	60 ± 1mm
D	13.0 ± 0.5mm

Notes

The tolerances unless mentioned ±0.1mm. Unit : mm ± 0.1

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2.1.3Label Form Specification

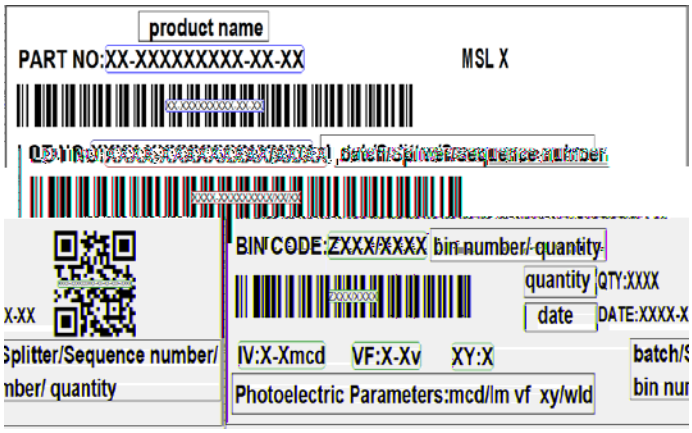

Fig. 2-3 Label Form Specification

able 2-2 Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
Φ	Luminous flux
XY	Chromaticity Bin
V_F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

2.2Moisture Resistant Packing

Fig.2-4Moisture Resistant Packing

2.3Cardboard Box

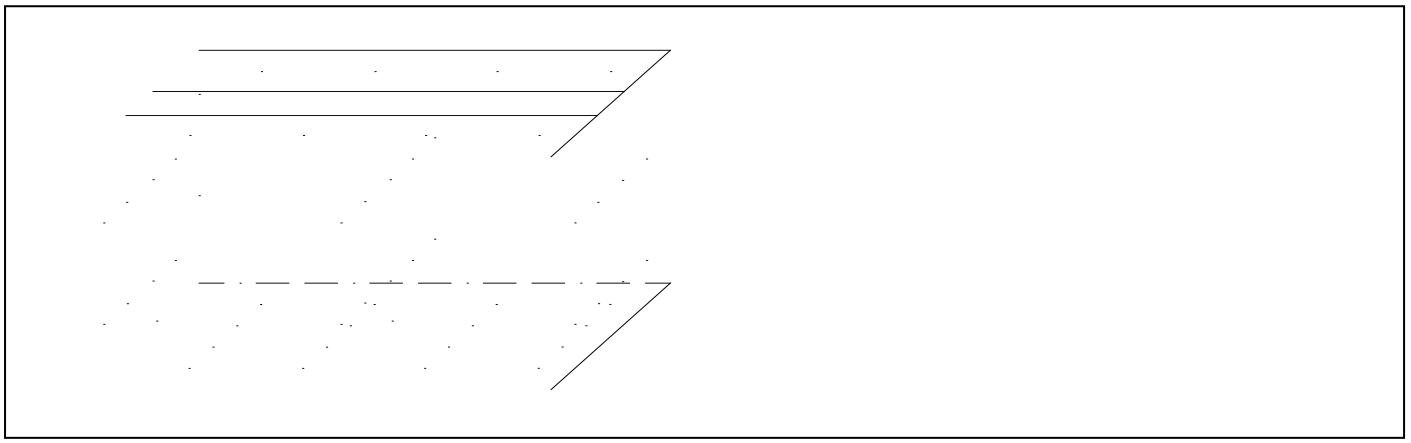

Fig.2-5Cardboard Box

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2.4Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
MSL2 2	JESD22-A113	85 / 60%R_H	168 hrs.	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min ↑↓10s 125 15min	1000 cycle	20pcs.	0/1
Life Test	JESD22-A108	Ta=105 IF=140mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%R_H IF=140mA	1000hrs.	20pcs.	0/1

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2.5 Criteria For Judging Damage

Table 2-4Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	IF=140mA	-	U.S.L*)x1.1
Reverse Current	I_R	V_R = 5V	-	U.S.L*)x2.0
Luminous Flux	Φ	IF=140mA	L.S.L*)x0.7	-

Notes

1.U.S.L: Upper standard level L.S.L: Lower standard level

2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions.d4(per8c 0.002and Ta=27±2.0℃) 3.We(n

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3. SMT Reflow Soldering Instructions SMT

3.1SMT Reflow Soldering Instructions SMT

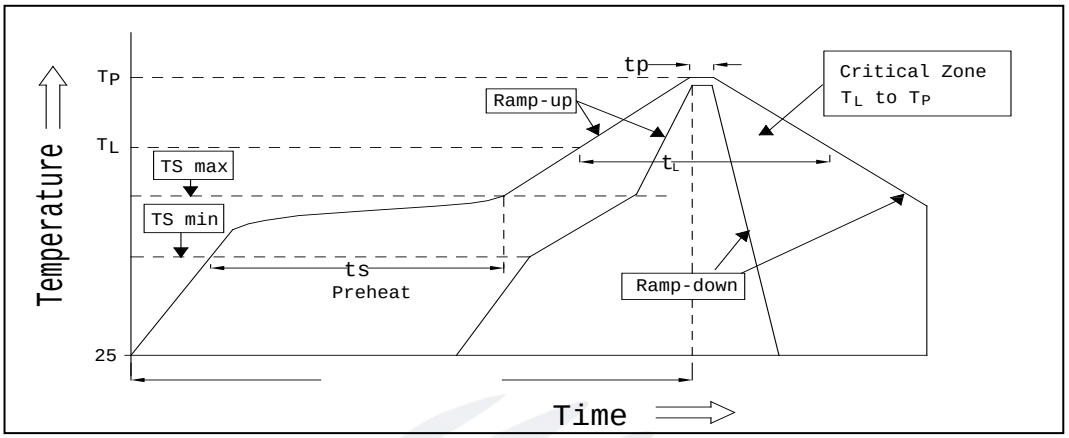

Fig.3-1SMT Reflow Soldering Instructions SMT

Table 3-1Reflow parameters

Average temperature rise speed Tsmax T_P	3 °C/ Max 3 °C/ s
Preheating: minimum temperature (Tsmin)	150 °C
Preheating: Max temperature (Tsmax)	200 °C
Preheating: Time Tsmin Tsmax	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature (T_L)	217 °C
Time limited to maintain high temperature: The Time (t_L)	60 Max 60s
Peak /Classification of temperature: / (T_P)	260 °C
Time limit classification of peak temperature time t_p	10 Max 10s
(T_P) 5 °C Hold time within 5 °C with the actual peak temperature (TP)	30 Max 30s
Cooling speed	6 °C/ Max 6 °C/ s
25 °C Needed time from 25 °C to Tp	8 Max 8 minutes

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Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings ,LED will be damaged. 24 LED

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED LED

3.1.2 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on

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Fig 4-1Cautions

(5) In designing a circuit,the current through each LED can not exceed the absolute maximum rating specified for each LED.In the mean while,resistors for protection should be applied,other wise slight voltage shift will cause big current change,burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF.If the reverse voltage is applied to LED, migration can be generated resulting in LED damage. LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline,such as brightness decreased,Color change and so on.Please consider the heat generation of the LEDs when making the system design.LED LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust,requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED

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Table 4-1Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	≤ 30	≤ 75%	Within 1 Year From Date
	After Opening Aluminum Bag	≤ 30	≤ 60%	Recommended for use within 24 hours 24
Baking		60 ± 5	-	≥ 24hours 24

(8) If the moisture absorbent material（silica gel）has faded away or the LEDs have exceeded the storage time,baking treatment should be performed after unpacking and based on the following condition（60±5）℃ for above 24 hours.

60 ± 5 24

If the package is flatulence or damaged,please notify the sales staff to assist.

(9)Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). LED

(10) Other points for attention, please refer to our relevant information.

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	Revisor	Version	Verifier	Remarks
20	Li xianhui	E0	Zhu yiming	New issue
19	Li xianhui	E1	Zhu yiming	Tj Update Tj

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Declare

This specification is written both in English and in Chinese and the latter is formal.

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